



BSI Standards Publication

Surface mounting technology

Part 3-1: Standard method for the specification of components for through hole reflow (THR) soldering — Guidelines for through hole diameter design with solder paste surface printing method

National foreword

This Published Document is the UK implementation of IEC TR 61760-3-1:2022.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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Published by BSI Standards Limited 2022

ISBN 978 0 539 17936 1

ICS 31.190

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This Published Document was published under the authority of the Standards Policy and Strategy Committee on 30 September 2022.

Amendments/corrigenda issued since publication

Date	Text affected
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